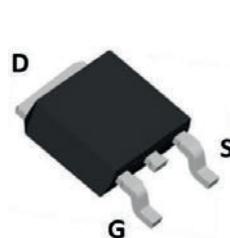
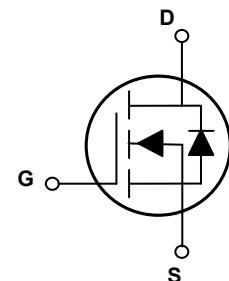


## Main Product Characteristics

$V_{(BR)DSS}$	60V
$R_{DS(ON)}$	35mΩ (typ.)
$I_D$	20A



TO-252 (DPAK)



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFD6046 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_A=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	20	A
Continuous Drain Current, @ Steady-State ( $T_A=70^\circ\text{C}$ )		15	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	80	A
Power Dissipation ( $T_A=25^\circ\text{C}$ )	$P_D$	40	W
Linear Derating Factor ( $T_A=25^\circ\text{C}$ )		0.32	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	14	mJ
Junction-to-Case	$R_{eJC}$	3.1	$^\circ\text{C}/\text{W}$
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{eJA}$	65	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V
Drain-to-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
		$T_J=125^\circ\text{C}$	-	-	50	
Gate-to-Source Forward Leakage	$I_{\text{GSS}}$	$V_{\text{GS}}=20\text{V}$	-	-	100	$\text{nA}$
		$V_{\text{GS}}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=6\text{A}$	-	35	46	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=4\text{A}$	-	38	50	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.1	1.6	2.6	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=10\text{V}, I_D=6\text{A}$	-	6	-	S
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}$ $F=1\text{MHz}$	-	1180	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	69	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	46	-	
Total Gate Charge	$Q_g$	$I_D=8\text{A}, V_{\text{DS}}=30\text{V}, V_{\text{GS}}=10\text{V}$	-	2.3	4.6	$\text{nC}$
Gate-to-Source Charge	$Q_{\text{gs}}$		-	15.6	22	
Gate-to-Drain ("Miller") Charge	$Q_{\text{gd}}$		-	3.9	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=30\text{V}, I_D=1\text{A}, R_{\text{GEN}}=6\Omega$	-	4.6	9.0	$\text{nS}$
Rise Time	$t_r$		-	14.8	28	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	26.2	52	
Fall Time	$t_f$		-	7.8	16	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	2.1	4.2	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	20	A
Pulsed Source Current (Body Diode)	$I_{\text{SM}}$		-	-	80	A
Diode Forward Voltage	$V_{\text{SD}}$	$I_s=4\text{A}, V_{\text{GS}}=0\text{V}$	-	1	1.2	V
Reverse Recovery Time	$T_{\text{rr}}$	$T_J=25^\circ\text{C}, I_F=1\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}$	-	14	28	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	10	20	nc

Note:

1. Pulse test: pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3.  $L=0.1\text{mH}, R_g=25\Omega, V_{\text{DD}}=25\text{V}, T_J=25^\circ\text{C}$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Typical Electrical and Thermal Characteristic Curves

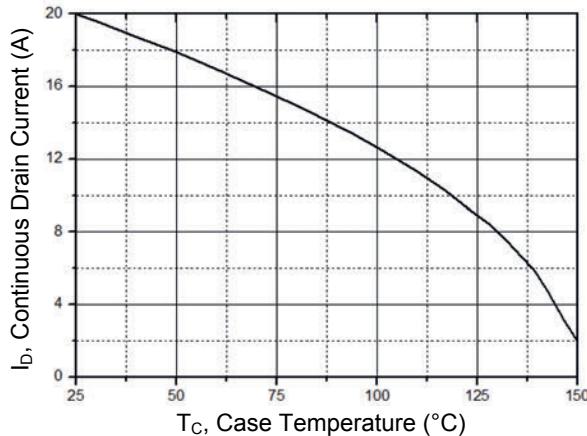


Figure 1. Continuous Drain Current vs. T<sub>c</sub>

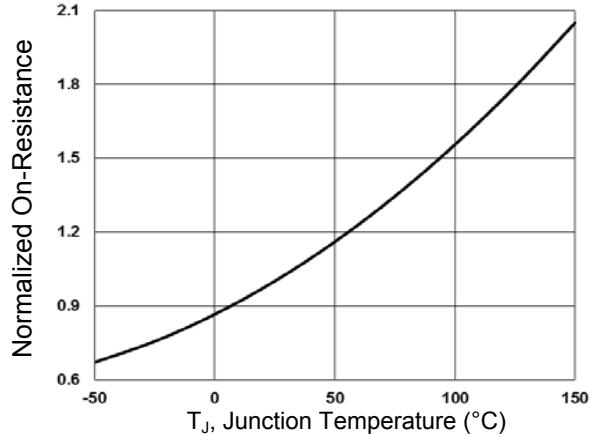


Figure 2. Normalized R<sub>DS(ON)</sub> vs. T<sub>j</sub>

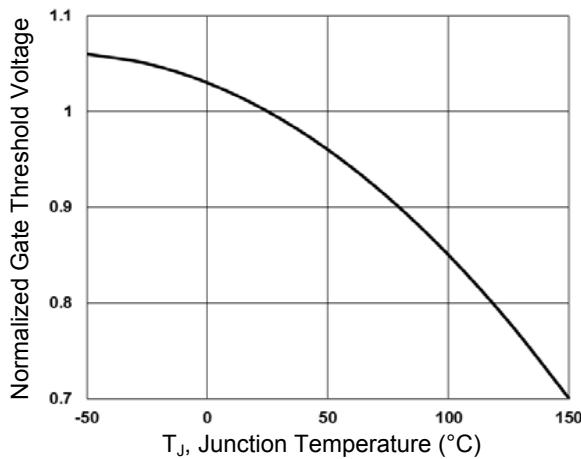


Figure 3. Normalized V<sub>th</sub> vs. T<sub>j</sub>

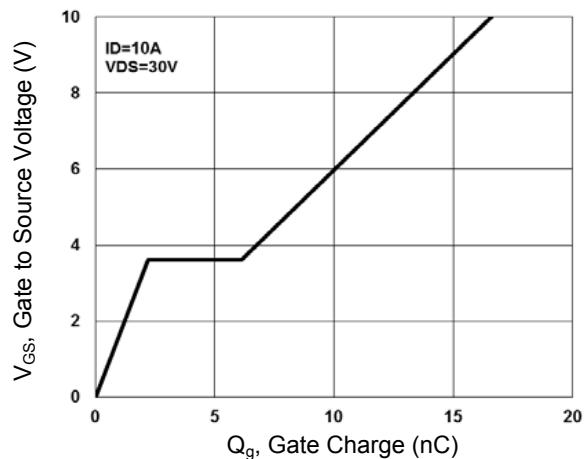


Figure 4. Gate Charge Waveform

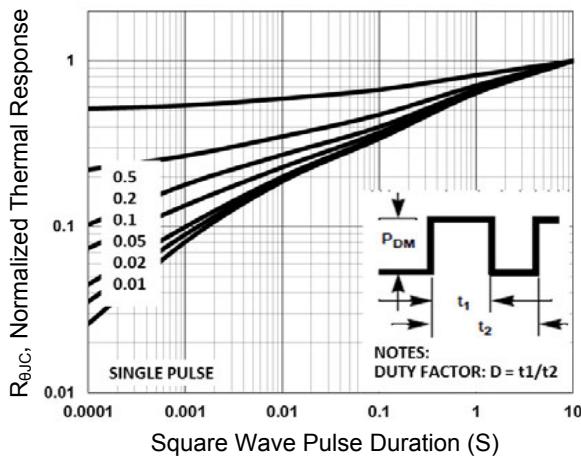


Figure 5. Normalized Transient Impedance

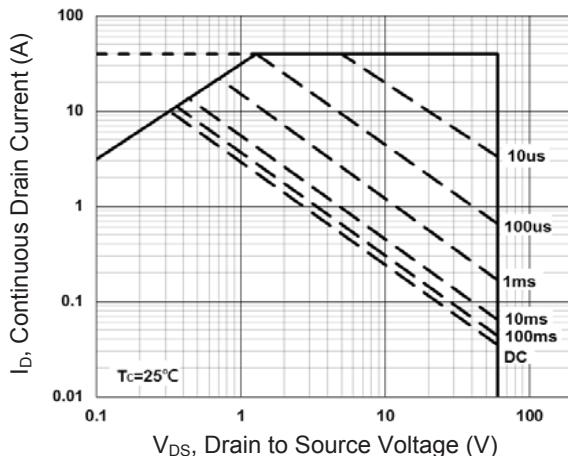
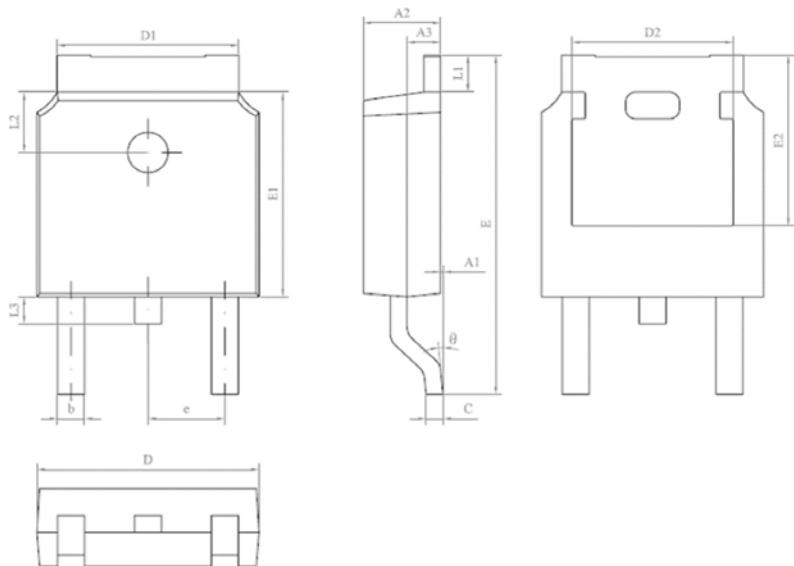


Figure 6. Maximum Safe Operation Area

**Package Outline Dimensions TO-252(DPAK)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.00	0.10	0.000	0.004
A2	2.20	2.40	0.087	0.094
A3	0.09	1.10	0.004	0.043
b	0.75	0.85	0.030	0.033
C	0.50	0.60	0.020	0.024
D	6.50	6.70	0.256	0.264
D1	5.30	5.50	0.209	0.217
D2	4.70	4.90	0.185	0.193
E	9.90	10.30	0.390	0.406
E1	6.00	6.20	0.236	0.244
E2	5.00	5.20	0.197	0.205
e	2.40	2.20	0.094	0.087
L1	0.90	1.25	0.035	0.049
L2	1.70	1.90	0.067	0.075
L3	0.60	1.00	0.024	0.039
θ	0°	8°	0°	8°